BGA Heat Sink - High Performance maxiFLOW/maxiGRIP-Low Profile





ATS Part#: **ATS-51250R-C1-R0**

Description: 25.00 x 25.00 x 19.50 mm BGA Heat Sink - High

Performance maxiFLOW/maxiGRIP-Low Profile

Heat Sink Type: maxiFLOW
Heat Sink Attachment: maxiGRIP

Equivalent Part Number: ATS-51250R-C2-R0 Discontinued

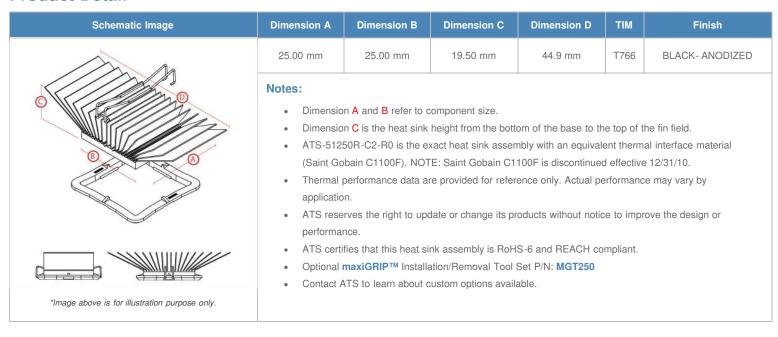
Features & Benefits

- maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- maxiGRIPTM attachment applies steady, even pressure to the component and does not require holes in the PCB
- Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards
- · Comes preassembled with high performance, phase changing, thermal interface material
- Designed for low profile components from 1.5 to 2.99mm

Thermal Performance

| AIR VELOCITY | | @200 LFM 1.0 M/S | @300 LFM 1.5 M/S | @400 LFM 2.0 M/S | @500 LFM 2.5 M/S | @600 LFM 3.0 M/S | @700 LFM 3.5 M/S | @800 LFM 4.0 M/S |
|--------------------|---------------|---------------------|---------------------|---------------------|---------------------|---------------------|---------------------|---------------------|
| THERMAL RESISTANCE | Unducted Flow | 3.8 °C/W | 3.1 °C/W | 2.7 °C/W | 2.4 °C/W | 2.2 °C/W | 2.1 °C/W | 2 °C/W |
| | Ducted Flow | 2.9 | N/A | N/A | N/A | N/A | N/A | N/A |

Product Detail







^{*}Image above is for illustration purpose only.